

Notice of References Cited

Application/Control No

09/938,150

Applicant(s)/Patent Under

Reexamination
OBENG ET AL.

Examiner

Anita K Alanko

Art Unit

1765

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U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-6,076,662	06-2000	Bahten, Kristan G	206/207
	B	US-6,454,634	09-2002	James et al.	451/41
	C	US-5,024,325	06-1991	Gundlach, Douglas P.	206/229
	D	US-5,698,455	12-1997	Meikle et al.	438/8
	E	US-6,361,409	03-2002	Vishwanathan et al.	451/56
	F	US-5,913,715	06-1999	Kirchner et al.	451/56
	G	US-6,352,595	03-2002	Svirchevski et al.	134/3
	H	US-6,468,911	10-2002	Miyashita et al.	438/692
	I	US-2002/0098789	07-2002	A. Burke, Peter	451/526
	J	US-2002/0098790	07-2002	Burke, Peter A.	451/528
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N	JP 2001047355 A	02-2001	Japan	HASEGAWA et al.	B24B 37/00
	O	AU 8665793 A	06-1988	Australia	CRAMPTON, L	A45D 29/17
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Li, W. et al "The effect of the polishing pad treatments on the chemical-mechanical polishing of SiO ₂ films" Thin Solid Films 270, pp 601-606, 1995.
	V	Li, I. et al "Dynamic Mechanical Analysis (DMA) of CMP pad materials" Mat. Res. Soc. Sump. Vol.613, pp E7.3.1-E7.3.10, 2000.
	W	Moinpour, M. et al "Advances in Characterization of CMP Consumables" MRS Bulletin 27 (10) 766-771, October 2002
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a))
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.